

# PS2702-1

HIGH ISOLATION VOLTAGE DARLINGTON TRANSISTOR SOP MULTI PHOTOCOUPLER SERIES

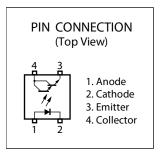
# DESCRIPTION

The PS2702-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon Darlington-connected phototransistor.

This is mounted in a plastic SOP (Small Out-line Package) for high density applications. This package has shield effect to cut off ambient light.

### FEATURES

- High current transfer ratio (CTR = 2 000% TYP.)
- High isolation voltage (BV = 3 750 Vr.m.s.)
- Small and thin (SOP) package
- High-speed switching ( $t_r = 70 \ \mu s \text{ TYP.}, t_f = 60 \ \mu s \text{ TYP.}$ )
- Ordering number of taping product: PS2702-1-F3
- Safety standards
  - UL approved: UL1577, Single protection
  - CSA approved: CAN/CSA-C22.2 No. 62368-1, Basic/Supplementary insulation
  - BSI approved: BS EN 62368-1, Basic/Supplementary insulation
  - VDE approved: DIN EN 60747-5-5 (Option)



#### **APPLICATIONS**

- Hybrid IC
- Telephone/FAX
- FA/OA equipment
- Programmable logic controllers

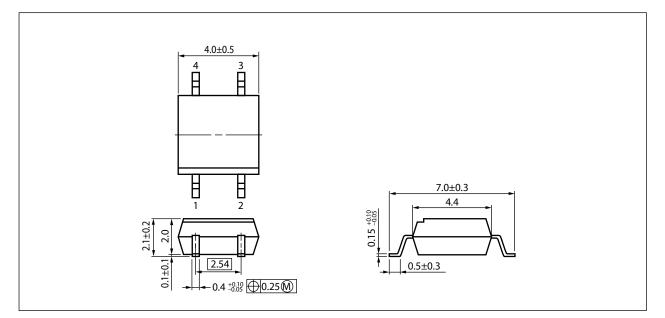
R08DS0099EJ0302

Rev.3.02

May 14, 2020



# PACKAGE DIMENSIONS (UNIT: mm)



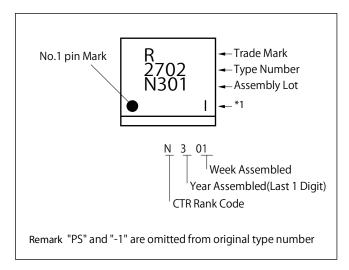
Weight: 0.08 g (typ.)

# PHOTOCOUPLER CONSTRUCTION

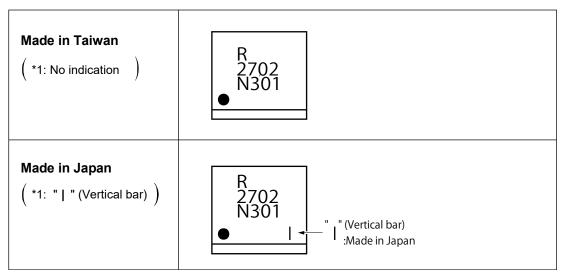
Parameter	Unit (MIN.)
Air Distance	5 mm
Creepage Distance	5 mm
Isolation Thickness	0.3 mm



#### MARKING EXAMPLE



Note: Bar indication contents of \*1.





#### **ORDERING INFORMATION**

Part Number	Order Number *1	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *2
PS2702-1	PS2702-1-A	Pb-Free	20 pcs (Tape 20 pcs cut)	Standard products	PS2702-1
PS2702-1-F3	PS2702-1-F3-A		Embossed Tape 3 500 pcs/reel	(UL, CSA, BSI, approved)	
PS2702-1-V	PS2702-1-V-A		20 pcs (Tape 20 pcs cut)	UL, CSA, BSI,	
PS2702-1-V-F3	PS2702-1-V-F3-A		Embossed Tape 3 500 pcs/reel	DIN EN 60747-5-5 approved	

Note: \*1. When specifying CTR rank, please add "/CTR rank" after Order Number. ex. L rank : PS2702-1-A /L

Note: \*2. For the application of the Safety Standard, following part number should be used.

#### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Forward Current (DC)	l <sub>F</sub>	50	mA
Reverse Voltage	V <sub>R</sub>	6.0	V
Power Dissipation Derating	⊿P <sub>D</sub> /°C	0.8	mW/°C
Power Dissipation	PD	80	mW
Peak Forward Current *1	I <sub>FP</sub>	1	A
Collector to Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter to Collector Voltage	V <sub>ECO</sub>	6	V
Collector Current	lc	200	mA
Power Dissipation Derating	⊿Pc/°C	1.5	mW/°C
Power Dissipation	Pc	150	mW
oltage *2	BV	3 750	Vr.m.s.
Ambient Temperature	T <sub>A</sub>	–55 to +100	°C
mperature	T <sub>stg</sub>	-55 to +150	°C
	Forward Current (DC) Reverse Voltage Power Dissipation Derating Power Dissipation Peak Forward Current <sup>*1</sup> Collector to Emitter Voltage Emitter to Collector Voltage Collector Current Power Dissipation Derating Power Dissipation	Forward Current (DC)IFReverse Voltage $V_R$ Power Dissipation Derating $\Delta P_D^{/\circ}C$ Power Dissipation Derating $\Delta P_D^{/\circ}C$ Power Dissipation $P_D$ Peak Forward Current *1 $I_{FP}$ Collector to Emitter Voltage $V_{CEO}$ Emitter to Collector Voltage $V_{ECO}$ Collector Current $I_C$ Power Dissipation Derating $\Delta P_C/^{\circ}C$ Power Dissipation Derating $BV$ Itage *2 $BV$	Forward Current (DC)IF50Reverse Voltage $V_R$ 6.0Power Dissipation Derating $\Delta P_D / ^{\circ}C$ 0.8Power Dissipation $P_D$ 80Peak Forward Current *1IFP1Collector to Emitter Voltage $V_{CEO}$ 40Emitter to Collector Voltage $V_{ECO}$ 6Collector CurrentIc200Power Dissipation Derating $\Delta P_C / ^{\circ}C$ 1.5Power Dissipation $P_C$ 150Dever Dissipation $P_C$ 150Ambient Temperature $T_A$ -55 to +100

Notes: \*1. PW = 100  $\mu$ s, Duty Cycle = 1%

<sup>\*</sup>2. AC voltage for 1 minute at  $T_A$  = 25°C, RH = 60% between input and output. Pins 1-2 shorted together, 3-4 shorted together.



# ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	$V_F$ $I_F = 5 \text{ mA}$		1.1	1.4	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5	μA
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		30		pF
Transistor	Collector to Emitter Dark Current	I <sub>CEO</sub>	I <sub>F</sub> = 0 mA, V <sub>CE</sub> = 40 V			400	nA
Coupled	Current Transfer Ratio $(I_C/I_F)^{*1}$	CTR	I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 2 V	200	2 000		%
	Collector Saturation Voltage	V <sub>CE (sat)</sub>	$I_{F} = 1 \text{ mA}, I_{C} = 2 \text{ mA}$			1.0	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time *2	tr	$V_{CC}$ = 5 V, $I_C$ = 2 mA, $R_L$ = 100 $\Omega$		70		μs
	Fall Time *2	t <sub>f</sub>			60		
	Turn-on Time *2	t <sub>on</sub>			90		
	Turn-off Time *2	t <sub>off</sub>			60		

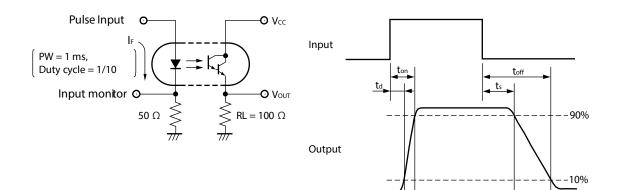
#### Notes: \*1. CTR rank

 K: 2 000 and larger
 (%)

 L: 700 to 3 400
 (%)

 M: 200 to 1 000
 (%)

\*2. Test circuit for switching time

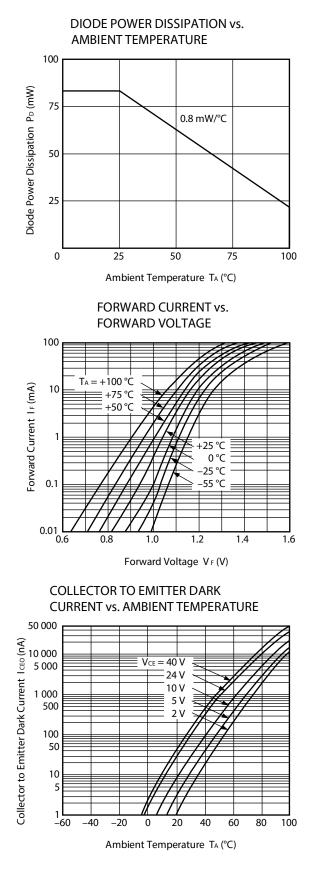


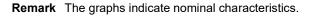
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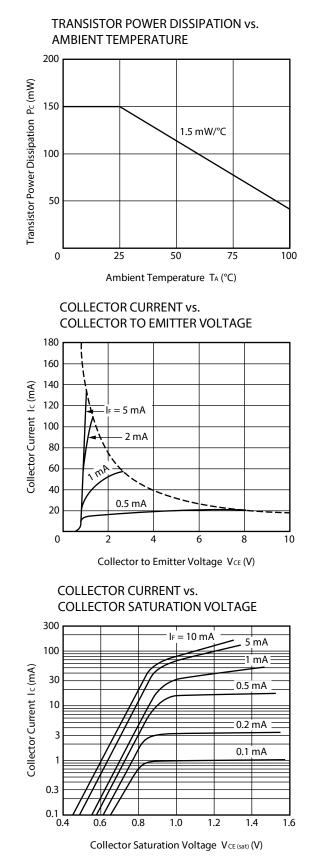


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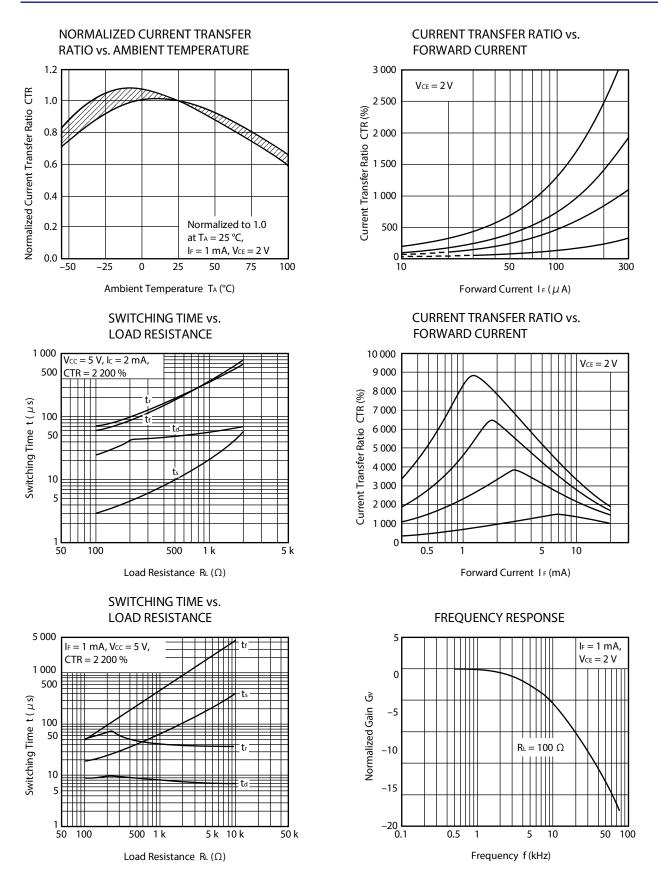
# TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, unless otherwise specified)





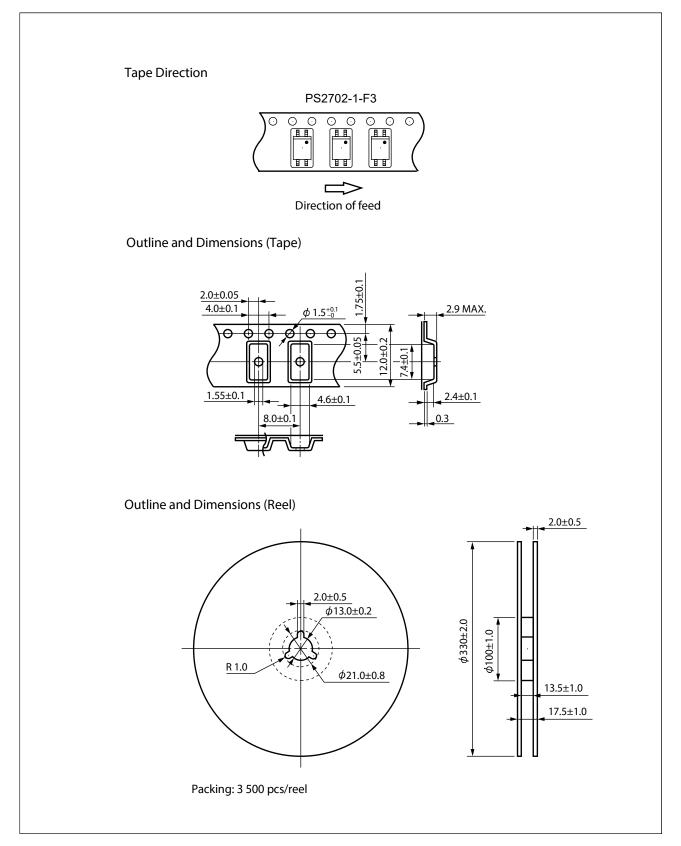






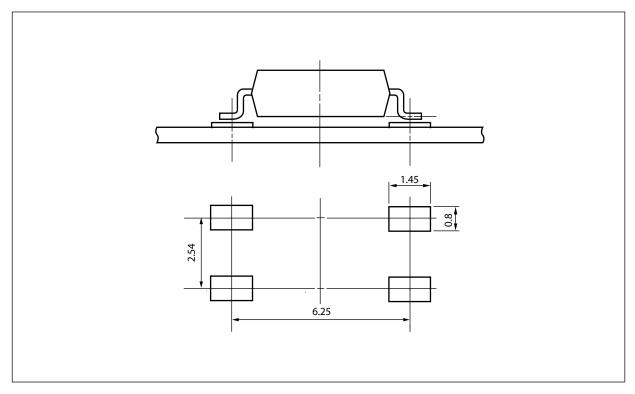
**Remark** The graphs indicate nominal characteristics.

# TAPING SPECIFICATIONS (UNIT: mm)





# RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



**Remark** All dimensions in this figure must be evaluated before use.



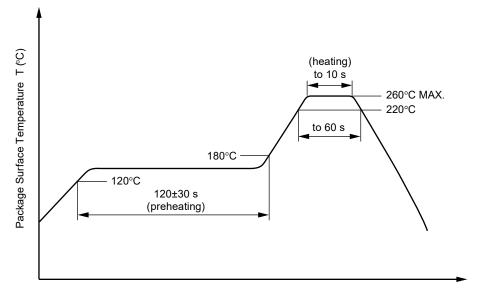
#### NOTES ON HANDLING

- 1. Recommended soldering conditions
  - (1) Infrared reflow soldering
    - Peak reflow temperature
    - Time of peak reflow temperature
    - Time of temperature higher than 220°C
    - Time to preheat temperature from 120 to 180°C
    - Number of reflows
    - Flux

#### 260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of

0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



#### Time (s)

- (2) Wave soldering
  - Temperature 260°C or below (molten solder temperature)
  - Time 10 seconds or less
  - Preheating conditions 120°C or below (package surface temperature)
  - Number of times One (Allowed to be dipped in solder including plastic mold portion.)
    - Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### (3) Soldering by Soldering Iron

Time (each pins)

• Peak Temperature (lead part temperature) 350°C or below

3 seconds or less

• Flux

Flux

- Rosin flux containing small amount of chlorine
- (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)
- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over 100°C

#### (4) Cautions

- Flux Cleaning
  - Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use fixing agents or coatings containing halogen-based substances.



#### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

 Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

#### **USAGE CAUTIONS**

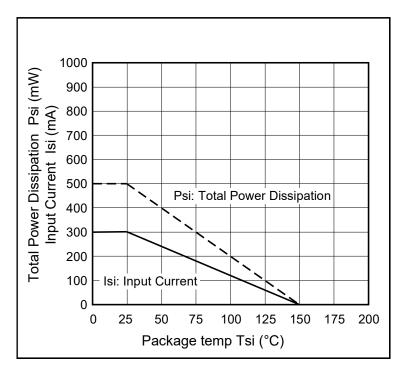
- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.
- 3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- 4. Do not use fixing agents or coatings containing halogen-based substances.



SPECIFICATION OF	VDE	MARKS	LICENSE	DOCUMENT
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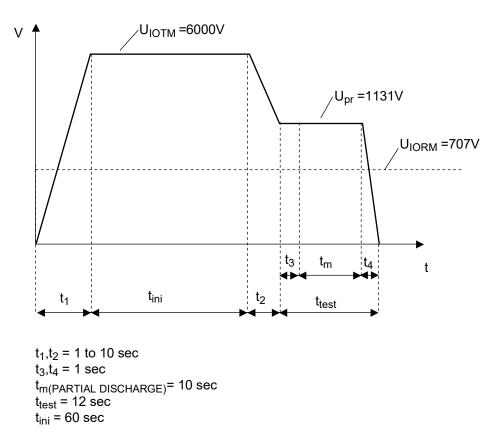
Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength			
maximum operating isolation voltage	UIORM	707	$V_{peak}$
Test voltage (partial discharge test, procedure a for type test and	Upr	1 131	$V_{peak}$
random test)			
$U_{pr}$ = 1.6 × $U_{IORM}$ , $P_d$ < 5 pC			
Test voltage (partial discharge test, procedure b for all devices)	Upr	1 325	V <sub>peak</sub>
$U_{pr}$ = 1.875 × $U_{IORM}$ , $P_d < 5 \text{ pC}$			
Highest permissible overvoltage	Uютм	6 000	V <sub>peak</sub>
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	СТІ	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	T <sub>stg</sub>	–55 to +150	°C
Operating temperature range	TA	–55 to +100	°C
Isolation resistance, minimum value			
$V_{IO}$ = 500 V dc at T <sub>A</sub> = 25°C	Ris MIN.	10 <sup>12</sup>	Ω
V <sub>IO</sub> = 500 V dc at T <sub>A</sub> MAX. at least 100°C	Ris MIN.	10 <sup>11</sup>	Ω
Safety maximum ratings (maximum permissible in case of fault, see			
thermal derating curve)			
Package temperature	Tsi	150	°C
Current (input current I <sub>F</sub> , Psi = 0)	lsi	300	mA
Power (output or total power dissipation)	Psi	500	mW
Isolation resistance			
V <sub>IO</sub> = 500 V dc at T <sub>A</sub> = Tsi	Ris MIN.	10 <sup>9</sup>	Ω

# Dependence of maximum safety ratings with package temperature

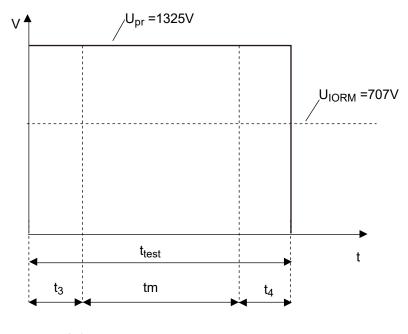








#### Method b) Non-destructive Test, 100% Production Test



 $\begin{array}{l} t_{3}, t_{4} = 0.1 \; \text{sec} \\ t_{m}(\text{PARTIAL DISCHARGE})^{=} \; 1.0 \; \text{sec} \\ t_{test} = 1.2 \; \text{sec} \end{array}$ 



Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	<ol> <li>Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> </ol>
	<ol><li>Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol>
	Do not burn, destroy, cut, crush, or chemically dissolve the product.
	Do not lick the product or in any way allow it to enter the mouth.

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